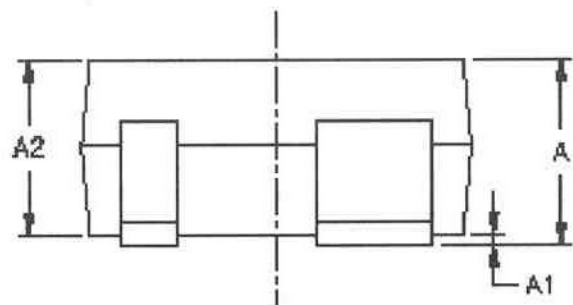


SYMBOL	MIN	MAX
e	0.65	BSC
D	1.80	2.25
b	0.15	0.40
b1	0.55	0.70
E	1.15	1.35
HE	1.80	2.40
Q1	0.10	0.40
A2	0.80	1.00
A1	0.00	0.10
A	0.80	1.10
c	0.10	0.18
L	0.10	0.30



**NOTE:**

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS ARE INCLUSIVE OF PLATING.
3. DIMENSIONS ARE EXCLUSIVE OF MOLD FLASH & METAL BURR.
4. ALL SPECIFICATIONS COMPLY TO EIAJ SC70.
5. DIE IS FACING UP FOR MOLD AND FACING DOWN FOR TRIM/FORM. 1b: REVERSE TRIM/FORM.
6. PACKAGE SURFACE TO BE MIRROR FINISH.

**Solitron**  
 PROPRIETARY INFORMATION  
 Devices, Inc.

TITLE  
 PACKAGE OUTLINE, SC70, 4L

APPROVAL \_\_\_\_\_ DOCUMENT CONTROL NO \_\_\_\_\_ REV 1/1